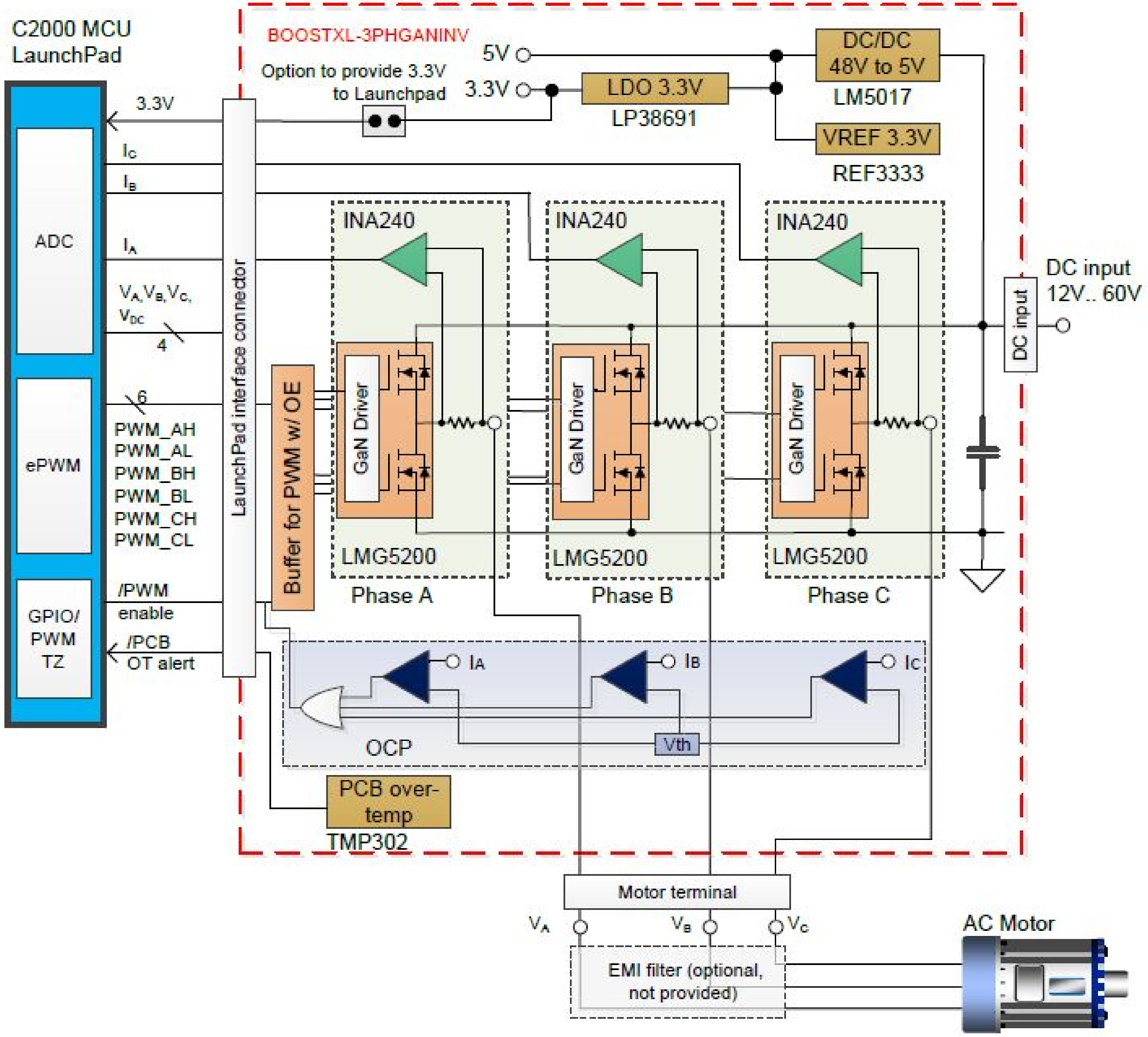
Revision History				
Rev	ECN #	Approved Date	Approved by	Notes
N/A	N/A	N/A	N/A	N/A



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Orderable: BOOSTXL-3PhGaNInv
TID #: N/A
Number: SENS007 Rev: A
SVN Rev: Not in version control
Drawn By:
Engineer: Zhou/Staebler

Designed for: Public Release
Mod. Date: 1/24/2018
Project Title: BOOSTXL-3PhGaNInv
Sheet Title:
Assembly Variant: 001
Sheet: 1 of 6
File: SENS007_BlockDiagram.SchDoc
Size: B
Contact: http://www.ti.com/support

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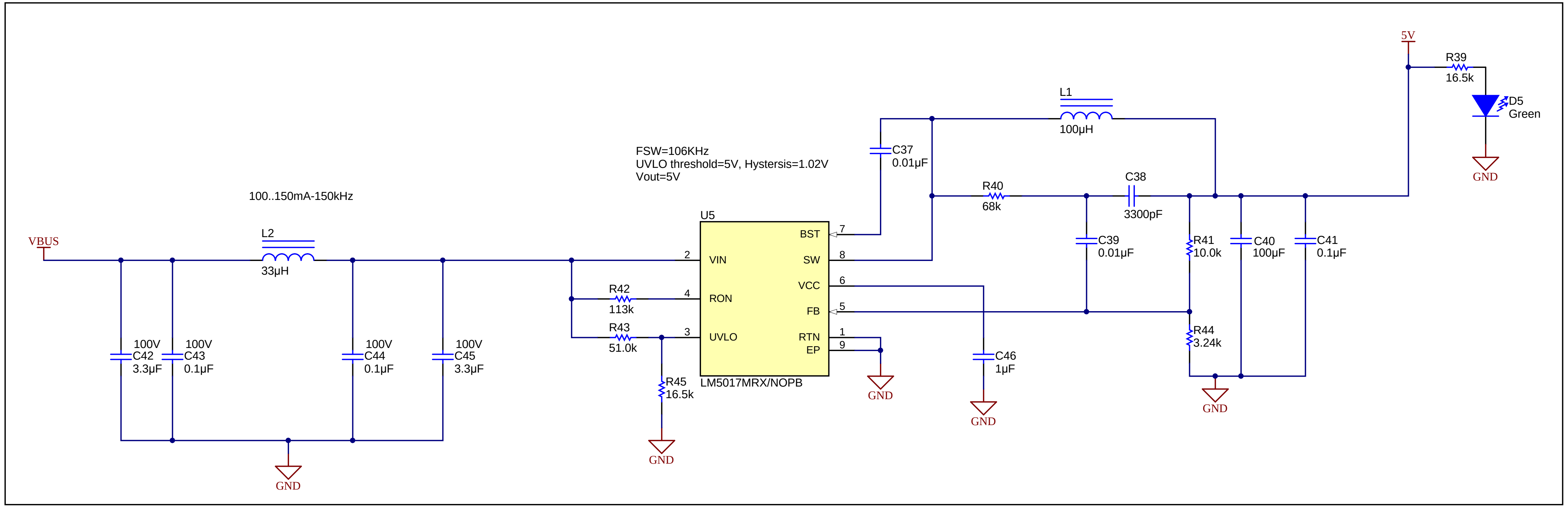
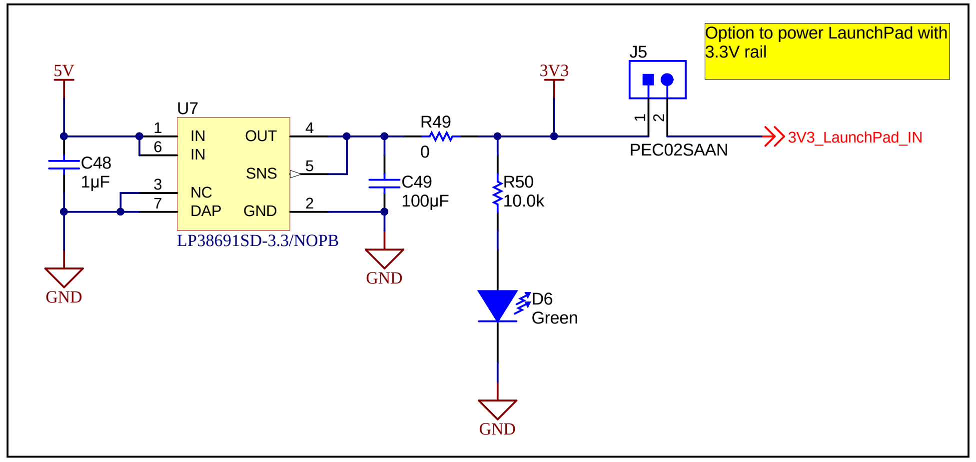
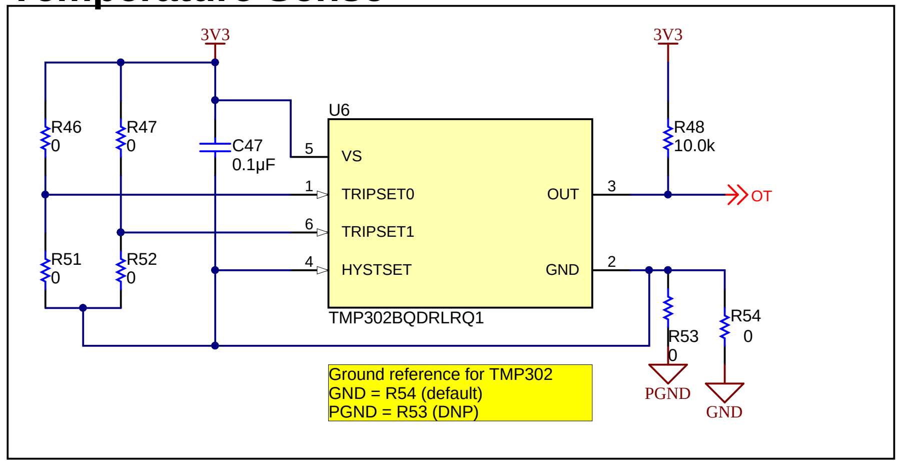
VBUS to 5V



5V to 3.3V



Temperature Sense



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Orderable: BOOSTXL-3PhGaNInv
TID #: N/A
Number: SENS007 Rev: A
SVN Rev: Not in version control
Drawn By:
Engineer: Zhou/Staebler
Designed for: Public Release Mod. Date: 1/24/2018
Project Title: BOOSTXL-3PhGaNInv
Sheet Title:
Assembly Variant: 001 Sheet: 2 of 6
File: SENS007_PS.SchDoc Size: B
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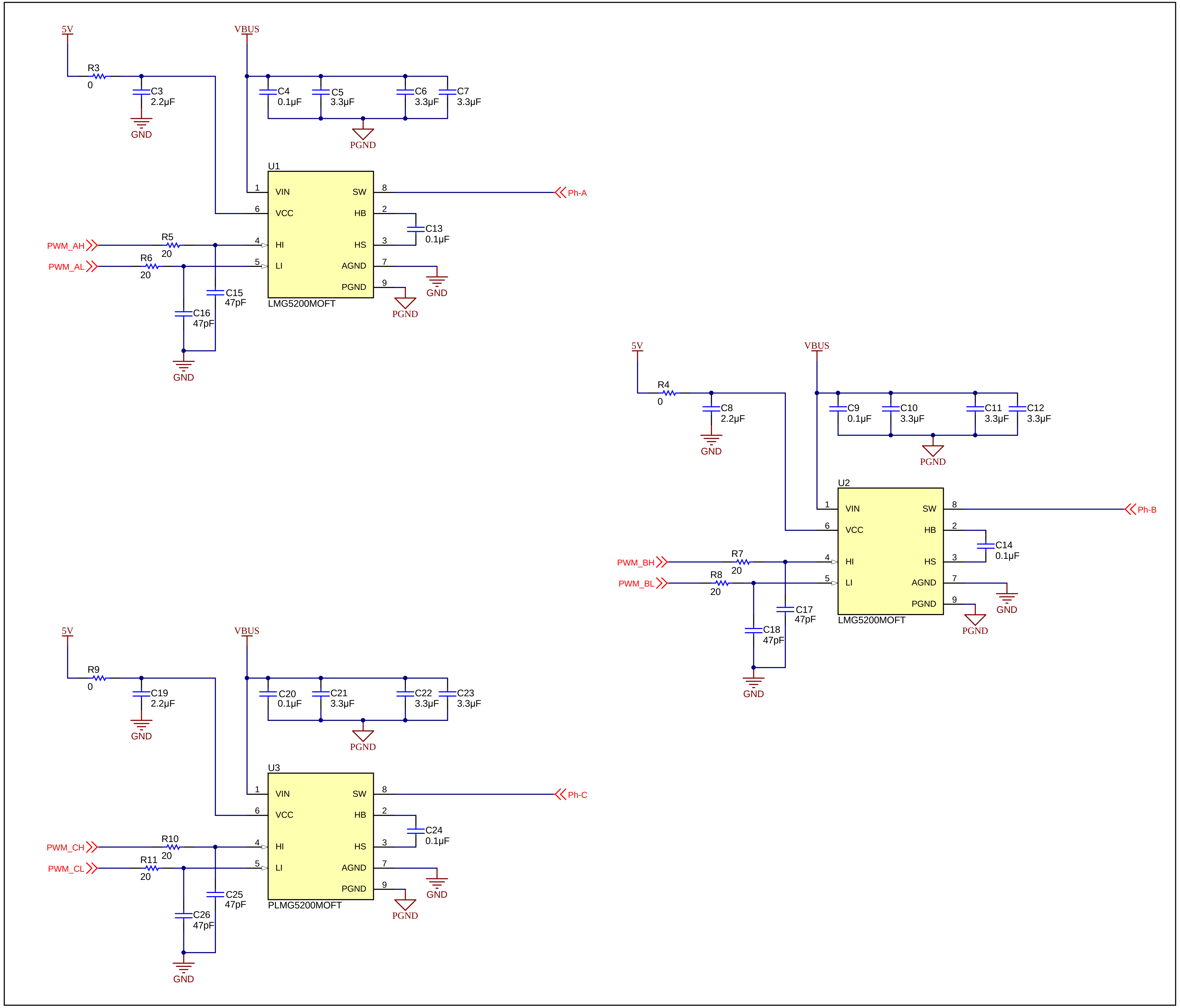
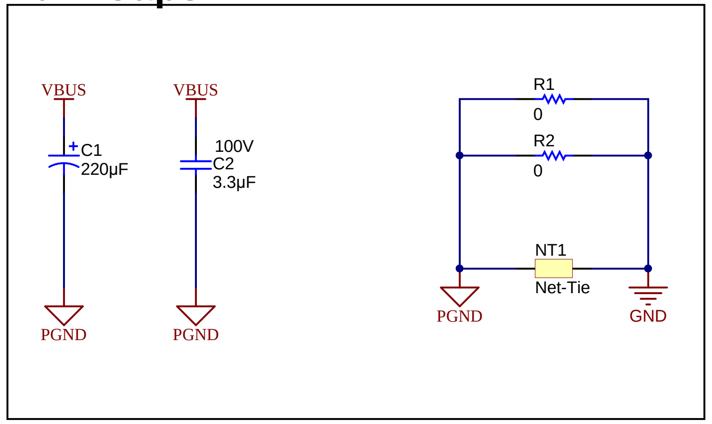
3Phase Inverter



Bulk Caps



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Orderable: BOOSTXL-3PhGaNInv	Designed for: Public Release	Mod. Date: 5/16/2017
TID #: N/A	Project Title: BOOSTXL-3PhGaNInv	
Number: SENS007 Rev: A	Sheet Title:	
SVN Rev: Not in version control	Assembly Variant: 001	Sheet: 3 of 6
Drawn By:	File: SENS007_GAN.SchDoc	Size: B
Engineer: Zhou/Staebler	Contact: http://www.ti.com/support	

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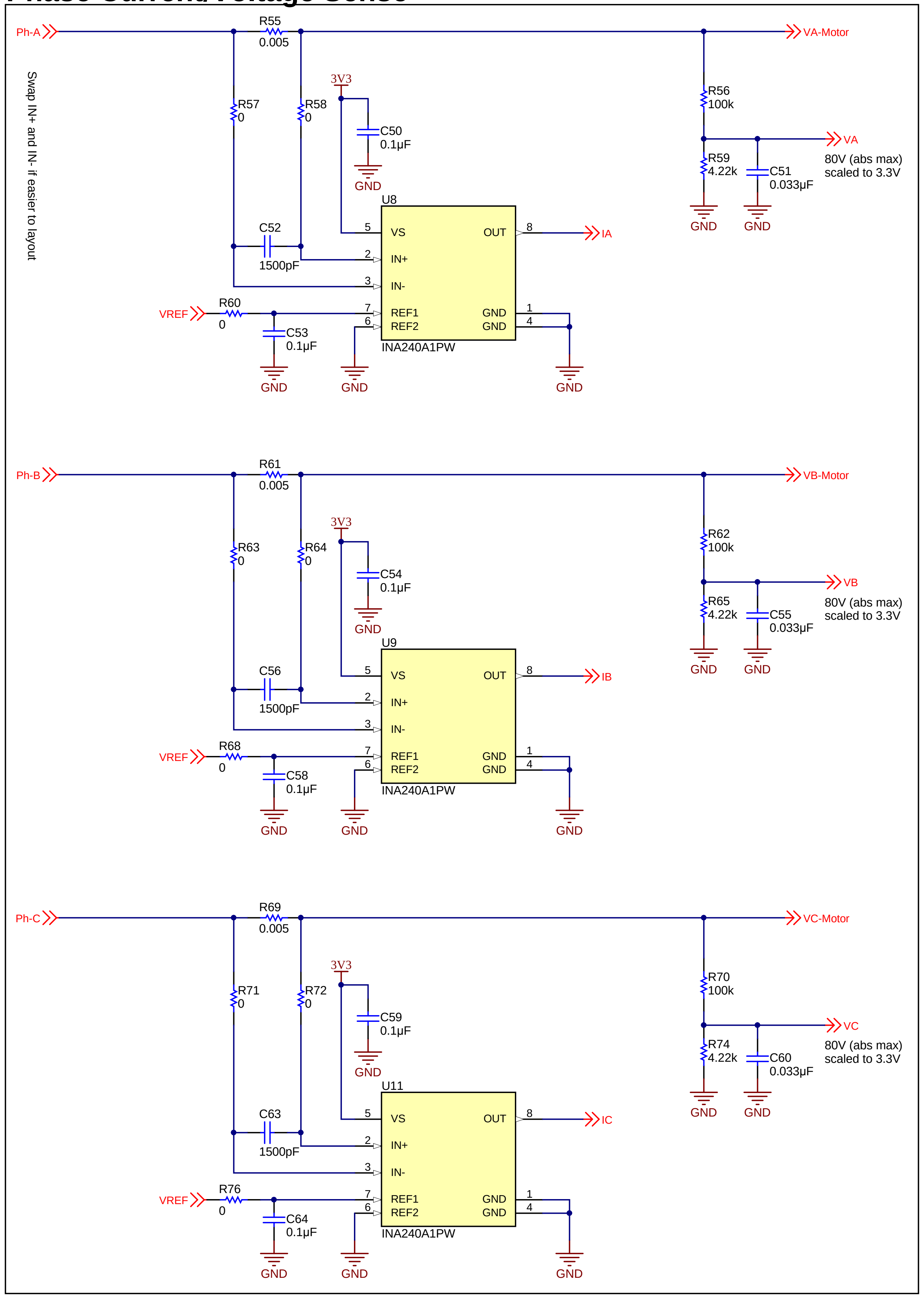
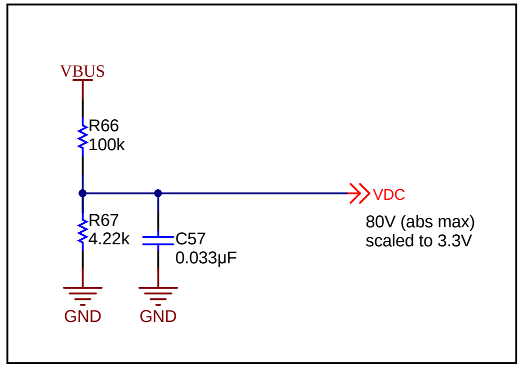
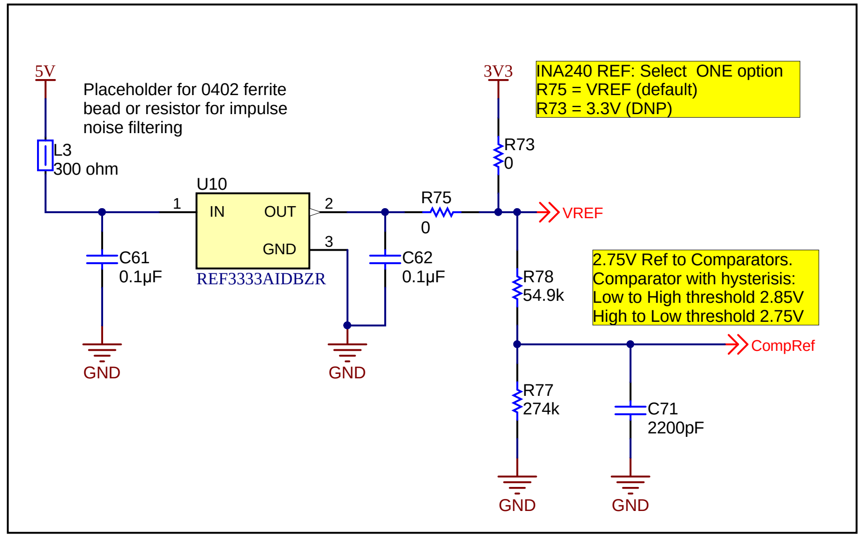
Phase Current/Voltage Sense



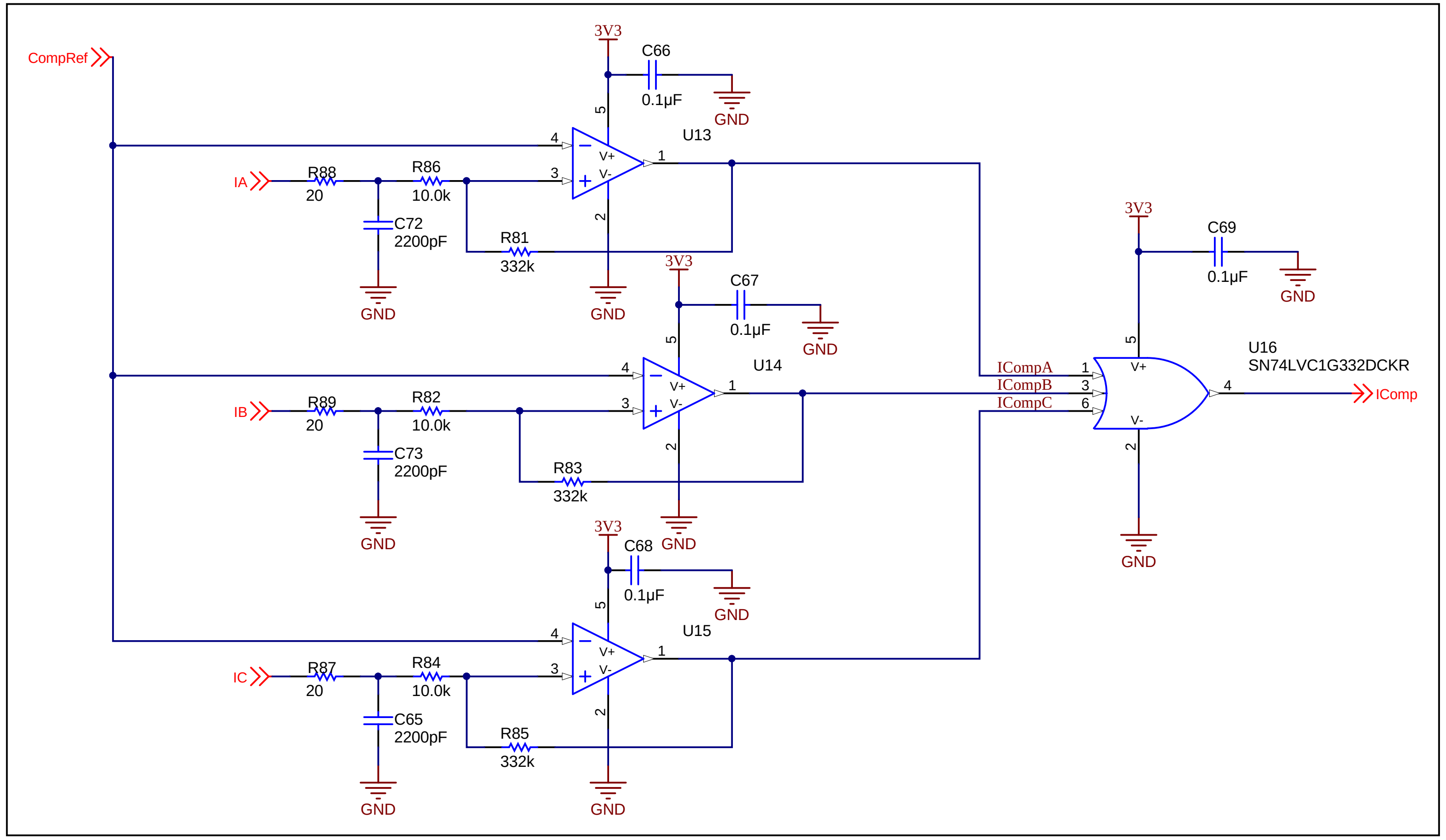
VBUS Sense



VREF



OCP



Orderable: BOOSTXL-3PhGaNInv
TID #: N/A
Number: SENS007 Rev: A
SVN Rev: Not in version control
Drawn By:
Engineer: Zhou/Staebler

Designed for: Public Release
Mod. Date: 1/24/2018
Project Title: BOOSTXL-3PhGaNInv
Sheet Title:
Assembly Variant: 001
Sheet: 4 of 6
File: SENS007_Sensing.SchDoc
Size: B
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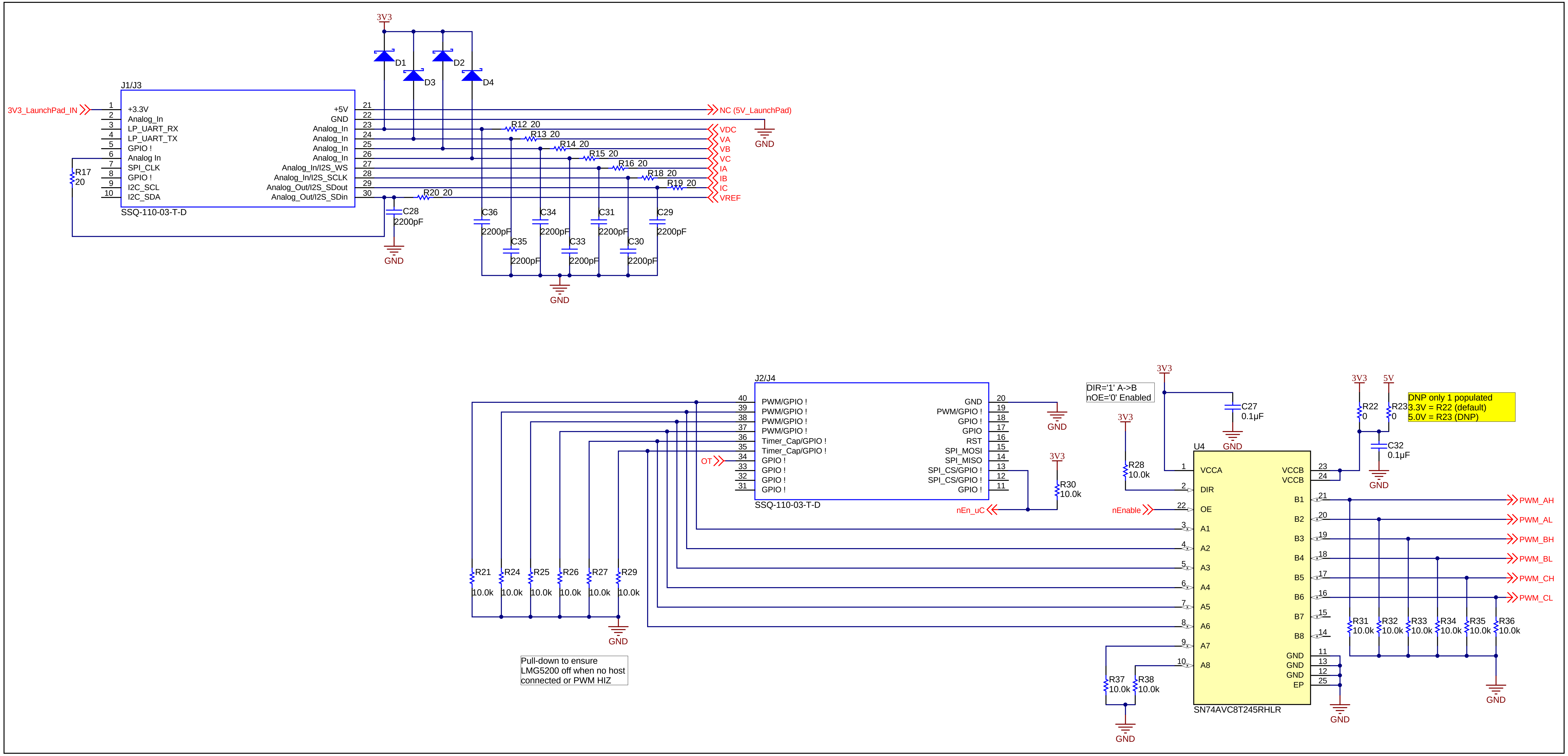
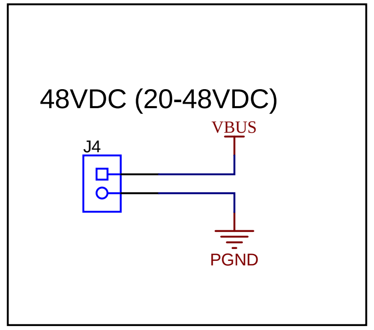
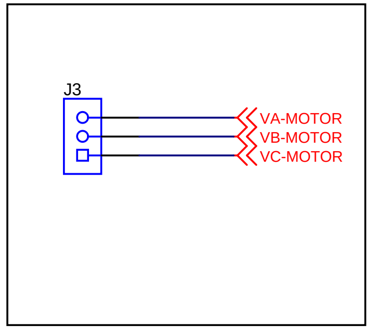
LaunchPad Connectors



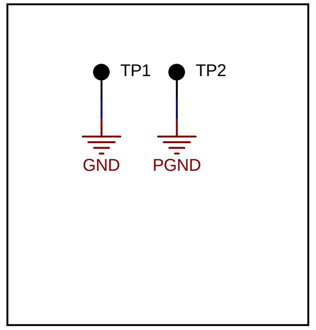
VBUS Connector



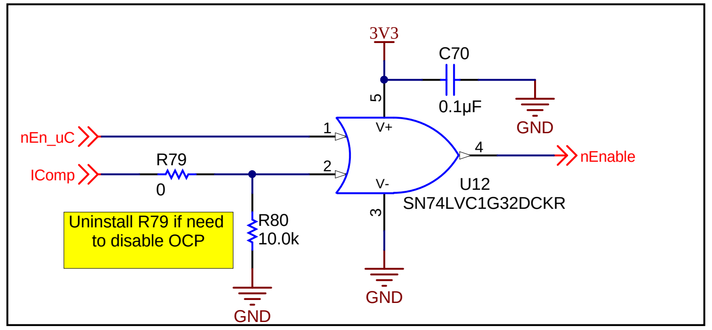
Motor Connector



TP



PWM Enable



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Orderable: BOOSTXL-3PhGaNInv	Designed for: Public Release	Mod. Date: 1/24/2018
TID #: N/A	Project Title: BOOSTXL-3PhGaNInv	
Number: SENS007 Rev: A	Sheet Title:	
SVN Rev: Not in version control	Assembly Variant: 001	Sheet: 5 of 6
Drawn By:	File: SENS007_Interface.SchDoc	Size: B
Engineer: Zhou/Staebler	Contact: http://www.ti.com/support	

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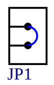

PCB
LOGO
Pb-Free Symbol

PCB
LOGO
FCC disclaimer

PCB Number: SENS007
PCB Rev: A

ZZ2
Assembly Note
These assemblies are ESD sensitive, ESD precautions shall be observed.

ZZ3
Assembly Note
These assemblies must be clean and free from flux and all contaminants. Use of no clean flux is not acceptable.

ZZ4
Assembly Note
These assemblies must comply with workmanship standards IPC-A-610 Class 2, unless otherwise specified.

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Orderable: BOOSTXL-3PhGaNInv		Designed for: Public Release	Mod. Date: 4/25/2017
TID #: N/A		Project Title: BOOSTXL-3PhGaNInv	
Number: SENS007	Rev: A	Sheet Title:	
SVN Rev: Not in version control		Assembly Variant: 001	Sheet: 6 of 6
Drawn By:		File: SENS007_HW.SchDoc	Size: B
Engineer: Zhou/Staebler		Contact: http://www.ti.com/support	

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